## Circuit Simulation of Sensors at HLL







Difference to process an device simulation on single devices often called a technology simulation

To distinguish to circuit simulation

Simulation of circuits (interplay of many devices)

input signals -> output signals

Drift Drain Clear DEPFET Gate Source separated different impl. in 2 overflow regions (OFR)

Based on design data

layer layout (Cadence: Virtuoso) design rule check (DRC) verification ? Comply with technology ? layout vs schematic (LVS) verification ? Comply with schematic ? (2 HLL Progress Reports given recently) schematic of circuit (Cadence)

mathematic models of all components and (single) devices

most interesting one: DEPMOS model has to be provided by us







In the past:

it was enough to invent and produce unique sensor devices pnCDDs, drift detectors, DEPFETs (difficult enough ... )

Today: competition by CMOS pixel sensors (produced in adapted technologies) especially for DEPFETs and pnCCDs

Design and production cutting edge sensors by making use of the full potential of our sensors

What can we gain by sensor circuit simulation?

- better understanding of limitations on sensors itself
   speed, S/N crucial parasitic components, design and/or technology adaptions ?
- optimization of interplay with control and readout electronics
   Goal: develop kind of **global models** of our most important sensors
   -> ASIC designers that they can provide tailored solutions

- easier interpretation of measurements





electric simulation of the entire signal path:

Switcher Read pulse -> signal propagation at gate line -> Depfet onset -> signal propagation at drain line -> DCD amplification

What do we need and what we have ?

Simulation models for switcher driving stages and DCD input stage (Ivan Peric, KIT)

RCL- model for gate/clear lines – extraction of parasitics (-> Andreas)

Depfet Model - Alex, Tuna, Sebastian started with a new model we gained some experience with an old quick and dirty approach

Put all things together (mixed technology simulation)



From layout data – Cadence tool: PEX

developed for planarized topologies what we do not have  $\ensuremath{\mathfrak{S}}$ 

We assume that is usable for fanin/fanout connections small errors: not many crossings, the bulk of capacitive load is the matrix

Depfet Matrix: much more topology

PEX extraction formulas will not work

different solutions



Looks more crucial as ist is y-scale / x-scale about 2





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Components

MOS transistor model

+

internal amplification clear process (further transistor) line (external) capacitances + resistances junction (internal) capacitances + resistances (contacts)

Requirements

numerically fast and clean precise (10% ?) physically motivated equations (predictive power over a large design and technology parameter space)

We started already and can learn from old attempts

#### Old Model MOST look up table

#### New Model Real MOST Parameter model





Measured at  $V_{cl high}$  (to keep internal Gate empty during static measurements)

For read mode  $V_{cl low}$ : correction of currents for Clear voltage needed



New lookup table for  $V_{cl}^{lo}$ :

$$n^{\text{Cl}} = 1.1 \ \mu\text{S}$$

$$I_{"0"}^{CLLo} = I_{"0"}^{CLHi} + \sqrt{\frac{I_{"0"}}^{CLHi}}{I_{"0"\text{Ref}}^{CLHi}} g_{m}^{CL} (10 \ V - V)^{CLLo} (10 \ V -$$





#### Old model:

#### 'Filling' the Internal Gate

$$I_{"1"}^{CLLo} = I_{"0"}^{CLLo} - \sqrt{\frac{I_{"0"}^{CLHi}}{I_{"0"}^{CLHi}}} g_{q} N_{SIG}$$

$$g_q = 400 \text{pA/electron}$$

- internal amplification 
$$@V_G = V_D = -5V$$

New model:  $g_q = f(w,L,tox,Id)$ 

## Old Clear Modul Ebers-Moll like diode eq.





Circuit simulator provides a time step  $\Delta t$ 

The model has to calculate the corresponding  $\Delta Q$  at the applied  $V_{CL}$ The new signal charge change  $I_d$  which is returned to the simulator.

$$\frac{\Delta Q}{\Delta t} = I_{c_0} (e^{y} - 1)$$
  

$$f = I_{c_0} (e^{y} - 1) - \frac{\Delta Q}{\Delta t}$$
 Search for the root (null) gives

Really quick and dirty - works but physical meaning ??

Needs revision:

Better subthreshold modell for n channel trans. (source follower mode)

 $\Delta Q$ 

# Belle line capacitances – 3d





Belle Layout gds data imported to Sentaurus Structure editor

3d simulation with Raphael field server

-> capacitance matrix

(Christian K.)

Expected efford for a new design: ca. 0.5 days

### Results for a Capacitive Coupled Clear Gate Pixel





Gate	
Source	Drain
Clear	C2 Cleargate C4 C3
o	$\downarrow C5$

cap label	net1	net2	cap [fF]
C1	Gate	Drain	8.7
C2	Cleargate	Drain	17
C3	Clear	Drain	4.5
C4	Clear	Cleargate	167
		All except	
C5	Clear	cleargate	56

For a pixel array 768x160: Cclear\_line = 100 \* 223fF = 22pF  $\uparrow$ Number of layout cells per row.

## • How to deal with junction caps (in silicon)







Old method: extraction by 3d device simulation

very cumbersome and time consuming  ${}^{\textcircled{}}$ 

Better methods? extraction like line caps. with a simple field server (only Laplace equ.) works for all reversed biassed junction

If MOS current is flowing ... standard situation look at Spice models







We want make circuit simulation running for HLL sensors

improve detector performance and better understanding of limiting mechanisms

Most challenging: DEPFET modelling and capacitance extraction

work in progress

ambitious and interesting task



# Backup slides

